Nov. 9, 2022 (Wed.)

	Monterosso (B1F)	Forum 1 (3F)	Forum 2 (3F)	Forum 3 (3F)	Vernaza (3F)
	Novel Package Substrate 1	**2.5D and 3D Interconnect 1**	**Package Materials and Process**	**Automotive and Power Electronics 1**	**Special Session 1**
Session Chair	**Dr. Jiho Joo**	**Prof. Bongyoung Yoo**	**Dr. Tae-Ik Lee**	**Prof. Jeong-Won Yoon**	
13:00 ~ 13:25	O1-1 Dr. Gwang-Mun Choi, Dr. Jiho Joo, Ki-Seok Jang, Jin-Hyuk Oh, Chanmi Lee, Dr. Ho-Gyeong Yun, Dr. Seok Hwan Moon, In-Seok Kye, Yoon-Hwan Moon, Dr. Kwang-Seong Choi, Dr. Yong-Sung Eom / Electronics and Telecommunications Research Institute (ETRI), Korea **"Selectively-Aligned Anisotropic Solder Film for Fine-Pitch Interconnections"**	(Invited) I1-1 Prof. Sanghwa Yoon / Hanyang University, Korea **"CMP-less Metal Planarization for 3D Interconnection"**	O1-2 Dr. Sumin Kang / Korea Institute of Machinery and Materials (KIMM), Korea Prof. Taek-Soo Kim / Korea Advanced Institute of Science and Technology (KAIST), Korea **"Mechanical Debonding of Thin Films for Advanced Electronic Applications"**	O1-3 Na-Rae Kim, Kwang-Hun Jeong, Prof. Jun-Hong Park / Hanyang University, Korea **"Measurement of Dynamic Properties of Multi-layered Semiconductors by Vibration Tests"**	13:00 ~ 15:00, **Ultrafine Pitch PCB Manufacturing and Interconnect Process** Tech University of Korea Korea Institute of Industrial Technology(KITECH) Korea Electronics Technology Institute(KETI) (Close Session)
13:25 ~ 13:50	O1-4 Dr. Wonyong Choi, Dr. David Bokwoo Han / Genesem Inc., Korea Prof. Keejun Han / Hansung University, Korea **"A Novel Selective EMI Shielding Process by Exploiting Tape Attach and Detach Sub-processes"**	(Invited) I1-2 Prof. Hyo-Jong Lee / Dong-A University, Korea **"Calculation of Copper Filling and Microstructural Analysis in TSV and PCB Patterns"**	O1-5 Doheon Kim, Gahui Kim, Prof. Young-Cheon Kim, Prof. Young-Bae Park / Andong National University, Korea **"Curing Condition Effects on the Interfacial Characteristics of Photosensitive Polyimide Capping Layer/ Cu RDL Structure"**	(Invited) I1-3 Dr. Dongjin Kim / Korea Institute of Industrial Technology (KITECH), Korea **"Heat-resistant Packaging Technologies of Wide Band-gap Power Modules"**	
13:50 ~ 14:15	(Invited) I1-4 Eita Horiki / Sekisui Korea Co., Ltd., Korea **"Build-up Dielectric Material that enables High Temp. Low Loss, High Toughness, High Yield Advanced FC-BGA Substrates"**	(Invited) I1-5 Prof. Myung Jun Kim / Kyung Hee University, Korea **"Additives in Cu Electrodeposition for TSV Filling"**	(Invited) I1-6 Mitsuo Sugino / Senju Metal Industry Co., Ltd., Japan **"Latest Soldering Material Technology for Semiconductor Assembly"**	(Invited) I1-7 Dr. Hanbyul Kang / Korea Automotive Technology Institute (KATECH), Korea (On-line Presentation) **"Reliability Challenges of Micro-electronics Packaging for Eco-friendly Car"**	
14:15 ~ 14:40	(Invited) I1-8 Kosuke Tsukamoto / Shinko Electric Industries Co., Ltd., Japan **"Demonstration of 2.3D Organic Package with Increased Interposer Size and Layer Count"**	(Invited) I1-9 Yong-Tae Kwon / Nepes Corp., Korea **"Die-stackable 3D Package Using Fan-out Technology"**	(Invited) I1-10 Hatakeyama Keiichi / Showa Denko Materials Co., Ltd., Japan **"Total Solution Activity of Showa Denko Materials for Future Advanced Semiconductor Packages"**	(Invited) I1-11 Dr. Semin Park / Hyundai Mobis Co., Ltd., Korea **"Power Semiconductor Module for Electrified Vehicles"**	
14:40 ~ 15:00	Coffee Break				
Session Chair	Prof. Sungdong Kim				
15:00 ~ 15:30	**Keynote Talk 1** - Prof. Sung Kyu Lim / Georgia Institute of Technology, USA (On-line Presentation) **"TSV & Heterogeneous Integration"** (Monterosso (B1F))				
15:30 ~ 16:00	**Keynote Talk 2** - Jing (Jim) Cao / Universal Scientific Industrial Co., Ltd., ASE Group, China (On-line Presentation) **"SiP, The Next Revolution for Microelectronics Packaging and The Challenges"** (Monterosso (B1F))				
16:00 ~ 16:20	Coffee Break				
	Monterosso (B1F)	**Forum 1 (3F)**	**Forum 2 (3F)**	**Forum 3 (3F)**	**Vernaza (3F)**
	Novel Package Substrate 2	**Emerging Technologies 1**	**Flexible and Printed Electronics 1**	**Automotive and Power Electronics 2**	
Session Chair	**Prof. Hyo-Jong Lee**	**Dr. Kwang-Seong Choi**	**Dr. Sung-Wook Mhin**	**Dr. Dongjin Kim**	
16:20 ~ 16:45	(Invited) I1-12 Hidetoshi Seki / Sumitomo Bakelite Co., Ltd., Japan **"Next-Generation Packaging Solutions for High-speed Communications"**	O1-6 Sung Min Jeon, Sang Yeob Kim, Sung Young Lee, Hyun-Jun Park, Byung-Geun Song, Mong-Hyun Cho, Dr. Jeong Tak Moon / MK Electron Co., Ltd., Korea **"High Reliability of Bonded Au Coated Ag Bonding Wire in Gas-free Condition"**	(Invited) I1-13 Prof. Yoonseok Park / Kyung Hee University, Korea (On-line Presentation) **"Wireless, Skin-interfaced Pressure Sensors for Biomedical Application"**	(Invited) I1-14 Dr. Zheng Zhang / Osaka University, Japan **"On-line Monitoring of the Health State of Power Assembly During Power Cycling by Using Acoustic Emission Technology"**	**Room Setting**
16:45 ~ 17:10	(Invited) I1-15 Dr. Minyoung Lim / LG Chem Ltd., Korea **"Novel Low Temperature Curable Photoimageable Dielectric Materials for Advanced Packaging"**	(Invited) I1-16 Dr. Kwang-Seong Choi / Electronics and Telecommunications Research Institute (ETRI), Korea **"Non-Fungible SITRAB (Simultaneous Transfer and Bonding) Technology for Commercialization of micro LED Displays"**	O1-7 Dr. Jagan Singh Meena, Su Bin Choi, Prof. Jong-Woong Kim / Jeonbuk National University, Korea Prof. Seung-Boo Jung / Sungkyunkwan University, Korea **"Highly Stable Textile-based Capacitor Strain Sensor for Human Motion Detection Application"**	(Invited) I1-17 Dr. Youngseok Kim / Hyundai Motor Company, Korea **"Design of Double Side Cooling Power Module Structure to Reduce Thermal Stress for Next Generation PE System"**	
17:10 ~ 17:35	(Invited) I1-18 Yoshinori Matsuura / Mitsui Mining and Smelting Co., Ltd., Japan **"Introduction of the Rigid Carrier Substrates with Releasing Function for 2.5D Organic Interposer Packaging Solutions"**	(Invited) I1-19 Prof. Keon Jae Lee / Korea Advanced Institute of Science and Technology (KAIST), Korea (On-line Presentation) **"Flexible Piezoelectric-sensor and MicroLED"**	O1-8 Eun Sung Oh, Dong Jun Kim, Dahye Lee, Dr. Hyeonjung Park, Jin-Woo Lee, Prof. Bumjoon J. Kim, Prof. Taek-Soo Kim / Korea Advanced Institute of Science and Technology (KAIST), Korea Dr. Tae-Ik Lee / Korea Institute of Industrial Technology (KITECH), Korea **"Thermo-mechanical Behavior of Poly (3-hexylthiophene-2,5-diyl) Thin Films for Flexible and Stretchable Electronics"**	(Invited) I1-20 Kuah Teng Hock, Eric / ASMPT Singapore Pte. Ltd. (ASMPT), Singapore **"Characterization of High Power Electronics Produced by ASMPT Pressure Sintering Solution for Automotive"**	
17:35 ~ 18:00	O1-9 Dr. Mohamed Lamine Faycal BELLAREDJ, Dr. Jeremy Streque, Dr. Goran Miskovic / Silicon Austria Labs (SAL), Austria **"Novel Lift-off based Process of Thick Copper Films on Organic Substrate for 5 μm Ultra-Fine Pitch Interconnects in Advanced Packaging"**	(Invited) I1-21 Dr. Hee Yeoun Kim / National NanoFab Center (NNFC), Korea **"Future of Wafer-level Packaging for Sensors : From Micro to Quantum"**	O1-10 Myoung Song, Dr. Boo Soo Ma, Seung Jin Oh, Prof. Taek-Soo Kim / Korea Advanced Institute of Science and Technology (KAIST), Korea **"Liquid Surface Platform for Quantitatively Evaluating Fracture Toughness of Ultra-Thin Gold Films"**	O1-11 Dr. Yong-Rae Jang, Prof. Hak-Sung Kim / Hanyang University, Korea Tae-Hwa Kim / Hyundai Motor Company, Korea Prof. Bongtae Han / University of Maryland, USA **"Life-prediction of Ag Sintered Die Attach Interconnects for SiC Power Module Semiconductor"**	
18:05 ~ 20:00	**Welcome Reception (2F)**				

Nov. 10, 2022 (Thu.)

	Monterosso (B1F)	Forum 1 (3F)	Forum 2 (3F)	Forum 3 (3F)	Vernaza (3F)
	Hybrid Bonding 1	**2.5D and 3D Interconnect 2**	**Flexible and Printed Electronics 2**	**Test and Reliability**	**Sponsor Session**
Session Chair	**Dr. Ah-Young Park**	**Prof. Hak-sung Kim**	**Prof. Suck Won Hong**	**Dr. Jiyong Park**	
9:00 ~ 9:25	(Invited) I2-1 Dr. Bo-mook Chung / YMT Co., Ltd., Korea **"Formation of Nanoscale Copper Roughness and Its Applications for Microelectronic Package Substrate"**	(Invited) I2-2 Dr. Seung-jae Yune / BSP Inc., Korea **"A Novel Technology for Crackless Through-Glass Via"**	(Invited) I2-3 Prof. Tae-il Kim / Sungkyunkwan University, Korea **"Unconventional Band Pass Filters for Bioelectronics"**	O2-1 Sang Il Kim, Dr. Dug Joong Kim, Prof. Hak-Sung Kim / Hanyang University, Korea Do-Hyung Kim, Dong-Min Jang, Dr. Jin Woo Jang, Seung Yeong Lee / Samsung Electronics Co., Ltd., Korea **"Corrosion Lifetime Prediction of Printed Circuit Board under Marine Atmosphere Condition Using Numerical Simulation Method"**	**Diamond** LG Chem | Hanwha NxMD Corporation **Platinum** Daeduck Electronics Co.,Ltd. HAESUNG DS Co., Ltd. | DISCO Corporation **Gold** YMT Co., Ltd. | SK hynix Inc. LB Semicon Inc. | LG Innotek Tokyo Electron Korea (TEL) Ltd. PSK Holdings Inc. **Silver** MK Electron Co., Ltd. | Genesem Inc. Woowon Technology Co., Ltd. Kostek Systems Inc. | Advanced Semiconductor Packaging Show **Booth** LG Chem | Hanwha NxMD Corporation OMA GOM | Nepes Corp. Next-generation Intelligence Semiconductor Foundation Woowon Technology Co., Ltd. LB Semicon Inc. | BSP Inc.
9:25 ~ 9:50	O2-2 Jia-Juen Ong, Dr. Dinh-Phuc Tran, Prof. Chih Chen / Natioanal Yang Ming Chiao Tung University, Taiwan Dr. Wei-Lan Chiu / Industrial Technology Research Institute (ITRI), Taiwan **"Reliability and Voids Analysis on Low Temperature nt-Cu/SiO2 Hybrid Bonds for Memory Stacking Applications"**	(Invited) I2-4 YiHak Lee / DuPont Electronics and Industrial, Korea **"Advanced Packaging Materials Solution for 3D Heterogeneous Integration"**	(Invited) I2-5 Prof. Wenlong Cheng / Monash University, Australia **"Gold Electronic Skins and Tattoos for Connected Healthcare"**	O2-3 Kyoungyeon Lee, JaeBeom Shim, ByongJin Kim, Dr. JinYoung Khim / Amkor Technology Inc., Korea **"Thermal Performance and Package Size Analysis by Design and Simulation"**	
9:50 ~ 10:15	(Invited) I2-6 Yong Chang Bum (Andy) / Applied Materials, Singapore **"C2W Stacked Die Bonding for Memory and Logic"**	(Invited) I2-7 Lewis(In-Soo) Kang / Nepes Corp., Korea **"Fanout Technology Based Antenna-in-package (FO-AiP) for 5G mmWave Application"**	O2-4 Prof. Benjamin Tee / National University of Singapore, Singapore **"Scaling Electronic Skins for Performance and Sustainability"**	(Invited) I2-8 Dr. Ralf Langhans / sentronics metrology GmbH, Germany **"Novel Wafer Metrology Center for Microelectronic Packaging Applications"**	
10:15 ~ 10:40	(Invited) I2-9 Lam Tak Wing, Percy / ASMPT Singapore Pte. Ltd. (ASMPT), Hong Kong **"Interconnect Solutions for Heterogeneous Intergradation"**	(Invited) I2-10 Prof. Eun-Ho Lee / Sungkyunkwan University, Korea **"Deep Learning Algorithm to Predict Anisotropic Thermal Conductivity of Three-dimensionally Connected Semiconductor Package Layers"**	(Invited) I2-11 Masayoshi Otomo / NAMICS Corporation, Japan **"Low Temperature Sintering Nano Silver Paste for Flexible Applications"**	O2-5 Dr. In-Seob Bae, Hong Chan Kim, Sung-Il Kang, Se Chuel Park / Haesung DS, Korea **"Board Level Reliability accroding to the Structure and Surface Finish of QFN Substrates"**	
10:40 ~ 10:50	Coffee Break				
10:50 ~ 11:10	**Opening Remark (Monterosso (B1F))**				
Session Chair	Prof. Sungdong Kim				
11:10 ~ 11:40	**Plenary Talk 1** - MJ (Myung-June) Lee / Intel Corporation, USA (On-line Presentation) **"Advanced Packaging Technologies and Roadmap"** (Monterosso (B1F))				
11:40 ~ 12:10	**Plenary Talk 2** - Dr. Amram Eitan / Taiwan Semiconductor Manufacturing Co., Ltd. (TSMC), Taiwan **"Bonding Technologies – Enabling Advanced Packaging"** (Monterosso (B1F))				
12:10 ~ 13:10	Lunch (2F)				
Session Chair	Prof. Young-Bae Park				
13:10 ~ 14:00	**Poster Presentation (Lobby (B1F & 3F))**				
Session Chair	Prof. Gu-Sung Kim				
14:00 ~ 14:30	**Keynote Talk 3** - Dr. Un-Byoung Kang / Samsung Electronics Co., Ltd., Korea **"Advanced Packaging Solution for Heterogeneous Integration - Status and Challenges"** (Monterosso (B1F))				
14:30 ~ 15:00	**Keynote Talk 4** - Dr. Jiho Kang / SK Hynix Inc., Korea **"An Overview of the Past, Present and Future of 3D Device Technology"** (Monterosso (B1F))				
15:00 ~ 15:20	Coffee Break				
	Monterosso (B1F)	**Forum 1 (3F)**	**Forum 2 (3F)**	**Forum 3 (3F)**	**Vernaza (3F)**
	Hybrid Bonding 2	**Emerging Technologies 2**	**Flexible and Printed Electronics 3**	**Special Session 2**	**Sponsor Session**
Session Chair	**Prof. Byungjoon Kim**	**Prof. Jae Yong Song**	**Prof. Tae-il Kim**		
15:20 ~ 15:45	(Invited) I2-12 Prof. Kyung Min Kim / Korea Advanced Institute of Science and Technology (KAIST), Korea **"Comprehensive Study on the Next-generation Chip-package Interface: Materials, Design, and Reliability"**	O2-6 Dr. Zhenfeng Li, Prof. Peng He, Dr. Shuye Zhang / Harbin Institute of Technology, China **"Recent Prospective and Challenges of 3D Heterogeneous Integration"**	(Invited) I2-13 Prof. Suckwon Hong / Pusan National University, Korea **"Tissue-interfaced Microelectronic Devices for Therapeutic Modulation"**	15:00 ~ 18:00, **Next-generation Electronic Packaging Materials** Electronics and Telecommunications Research Institute (ETRI) (Close Session)	**Diamond** LG Chem | Hanwha NxMD Corporation **Platinum** Daeduck Electronics Co.,Ltd. HAESUNG DS Co., Ltd. | DISCO Corporation **Gold** YMT Co., Ltd. | SK hynix Inc. LB Semicon Inc. | LG Innotek Tokyo Electron Korea (TEL) Ltd. PSK Holdings Inc. **Silver** MK Electron Co., Ltd. | Genesem Inc. Woowon Technology Co., Ltd. Kostek Systems Inc. | Advanced Semiconductor Packaging Show **Booth** LG Chem | Hanwha NxMD Corporation OMA GOM | Nepes Corp. Next-generation Intelligence Semiconductor Foundation Woowon Technology Co., Ltd. LB Semicon Inc. | BSP Inc.
15:45 ~ 16:10	(Invited) I2-14 Prof. Sungdong Kim / Seoul National University of Science and Technology (SEOULTECH), Korea **"Low Temperature Hybrid Bonding Technology for Heterogeneous Packaging"**	(Invited) I2-15 Seog Soon Kim / Unijet Co., Ltd., Korea **"Introduction of the Inkjet Printing Technology for Semiconductor Packaging"**	(Invited) I2-16 Prof. Sung Hun Jin / Incheon National University, Korea **"Physically Detachable and Operationally Stable Inorganic Perovskite Photodetector Arrays for Broadband Flexible Optical Systems"**		
16:10 ~ 16:35	(Invited) I2-17 Prof. Tadatomo Suga / Meisei University, Japan (On-line Presentation) **"The Surface Activated Bonding for 3D Heterogeneous Integration"**	(Invited) I2-18 Dr. Won-Seok Chang / Korea Institute of Machinery and Materials (KIMM), Korea **"Development of Nanoimprinting and Maskless Lithography System and Process with Improved Patterning Quality for Advanced Packaging"**	(Invited) I2-19 Prof. Yei Hwan Jung / Hanyang University, Korea **"Strain-unaffected Stretchable Wireless Electronics"**		
16:35 ~ 17:00	(Invited) I2-20 Dr. Thomas Glinsner / EV Group (EVG), Austria **"W2W Hybrid Bonding System for Next Generation Integration Scheme"**	O2-7 Jun-Sang Park, Gun-Hee Kim / Protec Co., Ltd., Korea **"Advanced Packaging Solutions with Dispensing System and Laser Assisted Bonding System"**	(Invited) I2-21 Prof. Ki Jun Yu / Yonsei University, Korea **"Unconventional Bio-integrated Electronics towards Human Machine Interface (HMI) Applications"**		
17:05 ~ 17:35	**General Meeting (Forum 1 (3F))**				
18:00 ~ 20:00	**Banquet and Headong Award Ceremony, Lucky Draw (Monterosso (B1F))**				

Nov. 11, 2022 (Fri.)

	Monterosso (B1F)	Forum 1 (3F)	Forum 2 (3F)	Forum 3 (3F)	Vernaza (3F)
	Emerging Interconnect	**Simulation and Modeling**	**Interconnect Reliability**	**Solder and PCB**	**Special Session 3**
Session Chair	**Prof. Hyunsik Yoon**	**Prof. Taek-Soo Kim**	**Prof. Yoonchul Sohn**	**Dr. Yong-Ho Ko**	
9:00 ~ 9:25	O3-1 Dr. Goran Miskovic, Dr. Mohamed Lamine Faycal Bellaredj / Silicon Austria Labs (SAL), Austria **"Influence of Silicon Substrate Rear Surface Modification on Silver-based Backside Metallization Stack for Die-attach Packaging Applications"**	O3-2 Jeong-Hyeon Baek, Dong-Woon Park, Prof. Hak-Sung Kim / Hanyang University, Korea Han-Sung Ryu, Gyung-Hwan Oh / Samsung Electronics Co., Ltd., Korea **"Warpage Simulation of Bi-material Strip by the Effective Cure Shrinkage Measurement of EMC Using Dielectric and FBG Sensors"**	O3-3 Xinyi Jing, Prof. Peng He, Prof. Shuye Zhang / Harbin Institute of Technology, China **"EBSD Analysis of BGA SAC305 300um Solder Ball at 1000 Cycles Thermal Shocks for Fan-out Wafer Level Packaging"**	O3-4 You-Gwon Kim, Heon-Su Kim, Prof. Hak-Sung Kim / Hanyang University, Korea Do-Hyung Kim, Dong-Min Jang, Dr. Jin Woo Jang, Seung Yeong Lee / Samsung Electronics Co., Ltd., Korea **"Prediction of Crack Type and Fatigue Life of Printed Circuit Board with Respect to Solder Composition under Repeated Thermal Cycle"**	**Room Setting**
9:25 ~ 9:50	O3-5 Woobin Kwon, Gahui Kim, Prof. Young-Bae Park / Andong National University, Korea Youn-Hye Kim, Yohei Kotsugi, Prof. Soo-Hyun Kim / Yeungnam University, Korea Yohei Kotsugi / TANAKA precious metals, Japan Dr. Kirak Son / Electronics and Telecommunications Research Institue (ETRI), Korea **"ALD TiN Diffusion Barrier Thickness Effects on the Interfacial Adhesion Energy for Ru Interconnects"**	O3-6 Jun Hwan Kim, Prof. Gil Ho Yoon / Hanyang University, Korea **"Multi-component Topology Optimization Considering Mesh-independent Connection"**	O3-7 Junmo Kim, Chang-Yeon Gu, Myoung Song, Prof. Taek-Soo Kim / Korea Advanced Institute of Science and Technology (KAIST), Korea Dr. Sung Woo Ma, Jin Hee Lee, Dr. Woong-Sun Lee / SK Hynix Inc., Korea **"Effect of Span-to-Depth Ratio on Bending Behavior of Thin Molded Underfill"**	O3-8 Dong-Woon Park, Myeong-Hyeon Yu, Prof. Hak-Sung Kim / Hanyang University, Korea **"Improvement of Assembly Reliability by Optimization of Pad Design on Printed Circuit Board"**	
9:50 ~ 10:15	O3-9 Hyeok-Jin Chu, Sungdong Kim / Seoul National University of Science and Technology (SEOULTECH), Korea **"Implementation of 4-Layer RDLs for FOWLP with Planarization of Polymeric ILD"**	O3-10 Heon-Su Kim, You-Gwon Kim, Prof. Hak-Sung Kim / Hanyang Univerisity, Korea Do-Hyung Kim, Dong-Min Jang, Dr. Jin Woo Jang, Seung Yeong Lee / Samsung Electronics Co., Ltd., Korea **"Prediction of Solder Fatigue Life of Package by Automated Parametric Modeling Simulation Technique"**	O3-11 Hui-Jin Um, Se-Min Lee, Hak-Sung Kim / Hanyang University, Korea Dae-Woong Lee, Sang-Yul Ha / SK Hynix Inc., Korea **"Study on the Mixed-mode Delamination of Epoxy Mold Compound (EMC)/Printed Circuit Board(PCB) Interface Considering Various Temperature and Moisture Absorption"**	O3-12 So-Yeon Jun, Tae-Young Lee, Sol-A Park, Dong-Gyu Choi, Jin-Kwan Kim, Sehoon Yoo / Korea Institute of Industrial Technology, Korea **"Rheology and wettability of solder paste with average solder powder size"**	
10:15 ~ 10:30	Coffee Break				
	Monterosso (B1F)		**Forum 3 (3F)**	**Forum 3 (3F)**	**Forum 1 (3F)**
	Young Engineers Forum		**Special Session 3**	**Special Session 4**	**Special Session 5**
10:30 ~ 12:30	**Young Engineers Forum** - Prof. Bongtae Han / University of Maryland, USA (Korean Language Session) **"Part I: History of Packaging Technologies and Perspective"** **"Part II: Engineering Chronic Problem - Why difficult to find its root causes?** (엔지니어링 고질적 문제 : 왜 근본 원인을 찾기 어려울까?)"		10:30 ~ 12:30, **Novel PCB Surface Finish for 5G/6G Package Application** MK Chem&Tech Korea Institute of Industrial Technology(KITECH) Tech University of Korea (Close Session)	10:30 ~ 12:30, **Strategy for Next Generation Semiconductor Package Techology** KMEPS (Close Session)	10:30 ~ 13:30, **AI Chiplet on Heterogeneous Integration Project: Design, Analysis, Interposer and Manufacturing** ETRI, SEMCO, AMKOR, KAIST, SEOULTECH, SNU, POSTECH, HANA Micron (Close Session)
12:30 ~ 12:45	**ISMP Award Ceremony, Lucky Draw and Closing Remark (Monterosso (B1F))**				

Poster Presentaion | Nov. 10, 2022 (Thu.) 13:10~14:00 P.M. Lobby (3F)

ID	Paper Title	Author	Affiliation	Country
1. Packaging Solutions for 5G/6G Applications				
P-001	Low-k Polymer Composite Ink Applied to Transmission Line	Hyun Jin Nam, Se-Hoon Park	Korea Electronics Technology Institute (KETI)	kr
P-002	Loss Analysis of Single Patch Antenna Using MPI in Sub-THz Band	Jaewoong Jung, Yunsik Park, Jongin Ryu	Korea Electronics Technology Institute (KETI)	kr
P-003	Study of S-Parameter Characteristics on Substrate Material in Trench Capacitor Structure for IPD	Seon-Kwon Kim, Hui-Geun Kang, Dong-Wook Kim, Jun-Seong Ji, Jung-Rae Park, Gu-Sung Kim	Kangnam University	kr
P-004	5G Filtering Power Divider using Substrate Integrated Waveguide Resonator with Multi-slots	Seunggoo Nam†, Se-Hoon Park	Korea Electronics Technology Institute (KETI)	kr
P-005	Transmission Lines Using Low-loss Material and Plasma Interface Treatments for Mm-wave	Jaewoo Song, Se-hoon Park	Korea Electronics Technology Institute (KETI)	kr
2. Electronic Materials for Interconnects and Packaging				
P-006	Interfacial Adhesion Energy between ALD Ru and Transition Metal Nitrides Diffusion Barrier for Advanced Interconnects	Daeyoon Jeong, Woobin Kwon, Youn-Hye Kim, Yohei Kotsugi, Gahui Kim, Kirak Son, Soo-Hyun Kim, Young-Bae Park	Andong National University, Yeungnam University, TANAKA precious metalsm, Electronics and Telecommunications Research Institute (ETRI)	kr
P-007	Stacked Through-hole Silicon Capacitors for High Density Applications	Su-Geun Kim, Seong-Jun Im, Hyun-Je Chang, Jong-Min Yook	Korea Electronics Technology Institute (KETI)	kr
P-008	Control of Size and Morphology of Dendrite-Shape Cu Particles and Improvement of Pressure-Assisted Sinter-Bondability	Sang-Hoon Jung, Jong-Hyun Lee	Seoul National University of Science and Technology	kr
P-009	Effects of Surface Treatment with Carboxylic Acids on Sinter Bonding Using Bimodal Cu Particles	Wan-Geun Lee, Jong-Hyun Lee	Seoul National University of Science and Technology	kr
P-010	Assessment of AF4 Parylene Adhesion on Si and SiO_2 Substrates by Means of Pull-off Energy	Taulant Sinani, Dmytro Solonenko, Goran Miskovic	Silicon Austria Labs (SAL)	at
P-011	Mechanical Reliability Improvement of Cu-Mn Interconnect for Flexible Electronics Through Self-forming Process	Jae-Myeong Shin, Seongi Lee, Won-Jun Lee, Young-Chang Joo, Byoung-Joon Kim	Tech University of Korea, Seoul National University, Sejong University	kr
3. Emerging Process for Interconnects and Packaging				
P-012	Properties of Various Plasma Surface Treatments for Oxide-oxide Bonding in 3D Integration	Sangmin Lee, Gwangsik Oh, Seungmin Park, Yoonho Kim, Sarah Eunkyung Kim	Seoul National University of Science and Technology	kr
P-013	Cu/Oxide Hybrid Bonding Analysis by Finite Element Modeling	Gwang-Sik Oh, Cha-Hee Kim, Won-Jun Lee, Jiho Kang, Jung Hwan Park, Young Su Yun, Sarah Eunkyung Kim	Seoul National University of Science and Technology, Sejong University	kr
P-014	In-situ Temperature-dependent Sheet Resistance of Cu Films in Oxygen Ambient for Wafer-Level 3D IC Integrations	Kyeong-Keun Choi, Sung-Kyu Kim	Pohang University of Science and Technology (POSTECH)	kr
P-015	Microstructures and Mechanical Properties of the Solder Joints of Sn-58Bi-xRu Alloys Reacted with ENIG and ENEPIG Surface Finishes	Ho-Ryul Shim, Yoonchul Sohn	Chosun University	kr
P-016	Comparative Study on the Microstructures and Mechanical Reliability of the Sn-58Bi-xPt Solder Joints Reacted with ENIG and ENEPIG Surface Finishes	Jun-Hyuk Bae, Yoonchul Sohn	Chosun University	kr
P-018	Demonstration of Ferrite core Embedded Solenoid Inductor Using LASER Modification Chemical Etching on Glass Substrate	Insub Han, Jongmin Yook, Jein Yu	Korea Electronics Technology Institute (KETI)	kr
P-019	A Basic Study on Laser Induced Plasma Monitoring for Selective Laser Ablation in Semiconductor Packaging Process	Geon-Min Kim, Jae-Heon Lee, Sang-Byuk Lee, Seung-Hwan Lee	Hanyang University	kr
P-020	Analysis of Microstructure of Solder Joint Using Anisotropic Solder Paste (ASP) and Laser-Assisted Bonding (LAB) Technology	Yoon-Hwan Moon, Yong-Sung Eom, Jiho Joo, Gwang-Mun Choi, Ki-Seok Jang, In-Seok Kye, Chanmi Lee, Jin Hyuk Oh, Yong-Jun Oh, Kwang-Seong-Choi	Electronics and Telecommunications Research Institute (ETRI), Hanbat National University	kr
4. PCB, Solder, and Assembly Process				
P-021	Design of Liquid Crystal Phase Shifter Using Copper Sheet	Deokjin Seo, Yunsik Park, Jongin Ryu	Korea Electronics Technology Institute (KETI)	kr
P-022	Enhancement on Electrochemical Migration Resistivity of Solder Joint by Ni-P Plating	Kyung Deuk Min, Byeong-Uk Hwang, Seung-Boo Jung	Sungkyunkwan University	kr
P-023	The Cu Electrochemical Polishing of Cu in Acid Solutions	Jinhyun Lee, Youjung Kim, Sukhbaatar Bayaraa, Yunha Song, Yang Fan, Wang Qing, Bongyoung Yoo	Hanyang University	kr
P-024	Effects of Cu-MWCNTs Composite Materials with Sn-3.0Ag-0.5Cu Solder on Mechanical Properties and Drop Reliability	DongGil Kang, TaeJoon Noh, JangBaeg Kim, Seung-Boo Jung	Sungkyunkwan University	kr
P-025	A Study of the Residual Stress Measurement on CCL for Package Substrate	Byoung-Phil Kang, Jong-Yun Lee, Jae-Sung Kim	Chungbuk National University, Simmtech Co., Ltd.	kr
P-026	Study of Electromigration-induced Failure in Ni/SnAg/Ni Microbumps by 3D X-Ray Laminography	Shih-Chi Yang, Chi-Hau Wu, Kai-Cheng Shie, Dinh-Phuc Tran, Chih Chen	National Chiao Tung University, National Yang Ming Chiao Tung University	tw
P-027	Study of Sn-Bi-In Ternary Solder Varying from Sn-Bi Eutectic Point to 79°C Ternary Eutectic Point	Hoon Choi, Hyeon-Dong Lee, Hoo-Jeong Lee	Sungkyunkwan University	kr
P-028	Microstructure and Joint Reliability in ENIG/Sn-3.5Ag/ENIG Sandwich Structure by Ultrasonic-assisted Soldering	Hyeon Tae Kim, Jeong-Won Yoon	Chungbuk National University	kr
P-029	Effects of Solder Volume on Interfacial Reaction and Mechanical Property of Sn-3.0Ag-0.5Cu Solder Joints During Multiple Reflows	Eun-Chae Noh, Young-Jin Seo, Jeong-Won Yoon	Chungbuk National University	kr
P-030	Brittle Fracture Properties of Sn-Ag-Cu Solders on Ni-free Electroless Palladium Immersion Gold (EPIG) Surface Finish for High Frequency Package Substrates	Tae-Young Lee, So-Yeon Jun, Deok-Gon Han, Tae-Ho Lee, Sehoon Yoo	Korea Institute of Industrial Technology (KITECH), MK Chem&Tech	kr
P-031	Development of High Ion Density and Uniformity Plasma Source for Large-scale Descum Processing	Dae-Chul Jung, Ho-Won Lee, Chin-Wook Chung	Hanyang University	kr
P-032	Interfacial Reactions and Properties of Pb-free Solder Joints Mixed Sn-Bi-Ag with Sn-Ag-Cu	Jahyeon Kim, Gyeongyeong Cheon, Youngran Choi, Dongjin Kim, Jungbin Choi, Young-Bae Park, Yong-Ho Ko	Korea Institute of Industrial Technology (KITECH), Andong National University, University of Science and Technology (UST)	kr
P-033	Study of Solder Joint Stability in Elevated Temperature Testing Condition of Sn-Ag-Cu-Ni-Bi Solder Composition on Cu-OSP Pad Finish at BGA PKG	J. Y. Son, J. W. Park, S. G. Lee, Y. W. Lee, S. B. Jung	Mk Electron Co., Ltd., Sungkyunkwan University	kr
P-034	A Study on X-shaped Through-Hole Filling Plating Technology for Stacking Package about Application of Pulse Plating and Organic Additives	Jeong-kyu Kim, Bo-Mook Jung, Dae-Geun Kim	YMT Co., Ltd.	kr
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P-035	A Study of Thermo-compression Bonded Ni-Sn Transient Liquid Phase Sinter-bonded Joints with Ultrasonic Time	Dong-Hwan Lee, Jeong-Won Yoon	Chungbuk National University	kr
P-036	Novel and Fast Transient Liquid Phase Bonding Using Cu Metal Foam/Sn-3.0Ag-0.5Cu Composite Solder Preform	Min-Haeng Heo, Jeong-Won Yoon	Chungbuk National University	kr
P-037	Comparative Study of Microstructure and Mechanical Properties of Ni-foam/SAC305 Composite Solder Joints	Young-Jin Seo, Jeong-Won Yoon	Chungbuk National University	kr
P-038	A Study on the Interfacial Properties and Mechanical Strength of Sintered Joints by Ratio of Bimodal Cu Paste	Junhyuk Son, Dong-Yurl Yu, Yun-Chan Kim, Shin-Il Kim, Min-Chan Kim, Hyunwoo Shin, Dongjin Byun, Junghwan Bang	Korea Institute of Industrial Technology (KITECH)	kr
P-039	A Study on High Level ASIL of System on Chip Packaging for Automotive Semiconductor	KyuBong Yeon, DuHo Lee	Korea Automotive Technology Institute (KATECH)	kr
P-040	A Study on the Dependability Characteristics of In-Vehicle Network in System on Chip Packaging for Autonomous Vehicle Valet Parking	KyuBong Yeon, DuHo Lee	Korea Automotive Technology Institute (KATECH)	kr
P-041	A Study on the PRUL (Prognostics of Remaining Useful Life) Sensor Packaging with Self-diagnostics for Automotive Functional Safety	KyuBong Yeon, DuHo Lee	Korea Automotive Technology Institute (KATECH)	kr
P-042	A Study on the ROA (Rear Occupant Alert) Sensor Packaging for Automotive In-Cabin Monitoring	KyuBong Yeon, DuHo Lee	Korea Automotive Technology Institute (KATECH)	kr
P-043	A Study on the SiC Semiconductor Package for Automotive PTC Heater System	KyuBong Yeon, DuHo Lee	Korea Automotive Technology Institute (KATECH)	kr
P-044	A Study on Heat Spreading Phase Change Composite	Hyeon Woo Son, Se Won Kim, Dong Rip Kim	Hanyang University	kr
P-045	A Buck-Boost Converter for Automotive Application in 208 Pin Quad Flat Package	Jun-Hwan Jang, Byong-Deok Choi	Hanyang University	kr
P-046	Critical Factors for Determining the Mechanical Properties on the Pressure-less Ag Nanoparticle Sintered Joints in Air	Seo Ah Kim, Min-Su Kim, Dongjin Kim	Korea Institute of Industrial Technology (KITECH)	kr
P-047	Highly Reliable Micro-Scale Cu Sintered Joint by Oxidation-Reduction Bonding Process under Thermal Cycling	Min-Su Kim, Dongjin Kim, Myong-Hoon Roh, Hiroshi Nishikawa	Korea Institute of Industrial Technology (KITECH), Osaka University	kr
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P-048	Triangular Beads like Structure of CuO and $CuCo_2O_4$ Decorated Nitrogen Doped Graphene Oxide for CWAs Simulant Detection	Sanjeeb Lama, Young-Jun Lee, Sivalingam Ramesh, Joo-Hyung Kim	Inha University, Dongguk University	kr
P-049	Design of Fluorescent Multi-Cancer Diagnostic Sensor Based on Microfluidic Devices	Byung Kwon Lee, Myung Yung Jeong	Pusan National University	kr
P-050	High Performance and Reusable SAW Sensor Coated with POSS-thiourea Based Polymer for DMMP Detection	Bong-Gyu Bae, Hee-Chan Jang, Young-Jun Lee, Joo-Hyung Kim	Inha University	kr
P-051	A Study on H_2O Free Low-temperature Metal Oxide Thin Film Process for Passivation Layer Using Atomic Layer Deposition	Yong-Tae Kim, Ho-Jae Ki, Jaeyeong Heo	Chonnam National University	kr
P-052	Effect of the Polyphosphonamide Based Sensing Materials for the Detection of CEES in SAW Sensor	Hee-Chan Jang, Bong-Gyu Bae, Young-Jun Lee, Joo-Hyung Kim	Inha University	kr
P-053	Characterization of Mini-LED Solder Joints after Multiple Laser Irradiation	In-Seok Kye, Yong-Sung Eom, Jiho Joo, Gwang-Mun Choi, Ki-Seok Jang, Chanmi Lee, Jin-Hyuk Oh, Yoon-Hwan Moon, Yong-Jun Oh, Kwang-Seong Choi	Electronics and Telecommunications Research Institute (ETRI), Hanbat National University	kr
P-054	Fabrication of Annulus Shaped Si Photodetector for Photoplethysmography	Keunhoi Kim, Yeeun Na, Tae Hyun Kim, Sang Hyun Park, Kyoungmin Kim, Hae Cheol Hwang, Minjun Bak, Eui-Je Jo, Nam Soo Park, Gapseop Sim, Byung Il Lee, Chang Hee Han, Soo-Hyun Kwon, Su Hyeon Kim, Jong-Bum You, Il-Suk Kang, Boo Taek Lim, Jongcheol Park	National Nano Fab Center (NNFC)	kr
P-055	Study on the Low Glass Transition Temperature and High Flame Retardancy of Detachable Polymer Coatings about $Mg(OH)_2$-silica Composite Aerogel	Kyu-Yeon Lee, Taehee Kim, Haryeong Choi, Hyung-Ho Park	Yonsei University	kr
P-056	NTC Behavior of the Spinel $Al_xMn_yNi_zCo_{3-x-y-z}O_4$ ($0 \le x \le 0.4$) for Temperature Sensor	Minju Kim, Sihyun Lee, Younghee So, Sungwook Mhin	Kyonggi University	kr
P-057	Effects of Yttria-doping on Silica Aerogels and Enabling Thermal Stability	Sanghyun Kim, Taehee Kim, Haryeong Choi, Hyung-Ho Park	Yonsei University	kr
P-058	Mass Transfer of Micro-LED Using a MEMS Vacuum Device	In-Joo Kim, Young Hak Cho, Sungdong Kim	Seoul National University of Science and Technology	kr
P-059	Polyurea Cross-linked Silica Aerogel with Improved Mechanical Strength by Introducing a Precursor Having Multiple Amino Groups	Wonjun Lee, Kyu-Yeon Lee, Sanghyeon Kim, Taehee Kim, Haryeong Choi, Hong-Sub Lee	Kangwon National University, Yonsei University, Kyung Hee University	kr
P-060	Synthesis Strategy and Improved Physicochemical Properties of Silica-based Aerogels Using Polyimide-based Cross-linking	Jiseung Kim, Sanghyeon Kim, Kyu-Yeon Lee, Taehee Kim, Haryeong Choi, Hong-Sub Lee	Kangwon National University, Yonsei University, Kyung Hee University	kr
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P-062	Highly Flexible and Efficient Solar Cell Module Designed Based on Numerical Analysis	Yuhwan Hwangbo, Xuan Luc Le, Xuan Bach Le, SungHoon Choa	Seoul National University of Science and Technology	kr
P-063	High Stretchable, Highly Sensitive Strain Sensor Fabricated with Ecoflex-MWCNTs Composite Paste and Ecoflex Substrate	Yuhwan Hwangbo, HyunJin Nam, SungHoon Choa	Seoul National University of Science and Technologyy, Korea Electronics Technology Institute (KETI)	kr
P-064	Effects of Bath Composition and Current Density on Fe-Ni Invar Electrodeposition Behavior	Na-Young Kang, Jae-Ho Lee	Hongik Universiy	kr
P-065	A Study on the Pressure Sensor Mounted onto the 3D Printed Prosthetic Socket for Motion Monitoring	Jun-Hee Park, Hyoung-Sub Shim, Sun-Kon Lee, Joo-Hyung Kim	Inha University	kr
P-066	Implantable Flexible Microelectronic Neural Interface Implemented by Mechanically Compliant Biomaterials for Brain Monitoring	Jeonghwa Jeong, Gyeonghwa Heo, Seon Yeong Chae, Suck Won Hong	Pusan National University	kr
P-067	Improvement of Opto-electronic Properties of Transparent Conductive Oxide Multilayers deposited by ALD and Sputtering Technique	Sujeong Kim, Jaeyeong HEO	Chonnam National University	kr
P-068	Optimization of Highly Stretchable Electrode Designs for 2D Array Substrate Based on Finite Element Analysis	Ah-Young Park, Sumin Kang, Hakyung Jeong, Jun-Yeob Song, Jae Hak Lee, Seungman Kim, Seongheum Han	Korea Institute of Machinery and Materials (KIMM)	kr
P-069	Reliability Evaluation of Conductive Fiber for Wearable Electronics	Seung Hyeok Lee, Juwon Jun, Mi Jung Lee, Youn Hee Kim, Byoung-Joon Kim	Tech University of Korea	kr
P-070	Effect of Flexible Substrate on Elastic Modulus Measurement of Metallic Thin-film During Nanoindentation	Hyejin Son, Jong-Hyup Lee, Soo-Hyun Kim, Byoung-Joon Kim, Young-Cheon Kim	Andong National University	kr
P-071	Mechanical Characterization of Laser Transmission Welding for Polymer Substrates	Myeong-Jun Ko, MinJeong Sohn, Dong-Yurl Yu, Jeehoo Na, BeomSeok Kang, Young-Bae Park, Tae-Ik Lee	Korea Institute of Industrial Technology (KITECH), Andong National University, Korea University	kr
P-072	Printable Soft Silicone Packaging for Wearable Devices	Si Won Park, Min Ku Kim	Hanyang University	kr
P-073	An Investigation of the Homogeneous ZnO P-n Junction Formed by Continuous Atomic Layer Deposition Process	Dong-eun Kim, Minjae Kim, Akendra Singh Chabungbam, Atul Thakre, Hyung-Ho Park	Yonsei University	kr
P-074	Enhanced Electrochemical Performance of Single-Crystal LiNi0.8Co0.1$Mn_{0.1}O_2$ by Atomic Layer Deposition	Yongseok Lee, Seunghoon Nam	Andong National University	kr
P-075	Pillar Structure on PDMS-based Electrodes for Stretchable Electronics	Sungwook Mhin, Kyu-bong Jang, Kyoung Ryeol Park, Sehoon Yoo	Kyonggi University, 2Korea Institute of Industrial Technology (KITECH)	kr
P-076	Fabrication of Flexible and Self-Healing Heaters Comprising Electrospun Polycaprolactone Fibers and $Ti_3C_2T_X$ MXene/AgNW Electrode	Su Bin Choi, Jagan Singh Meena, Seung-Boo Jung, Jong-Woong Kim	Jeonbuk National University, Sungkyunkwan University	kr
P-077	Mechanical Characteristic of Fast-cured Polydimethylsiloxane at Low Temperature for Highly Stretchable Electronic Device	Hakyung Jeong, Ah-Young Park, Seung Man Kim, Jun-Yeob Song, Jae Hak Lee	Korea Institute Machinery and Materials (KIMM)	kr
P-078	Low-cost and Highly Sensitive of Flexible Pressure Sensors Based on Graphite Paste Through O2 Plasma Surface Treatment Process	Hyun Jin Nam, Se-Hoon Park	Korea Electronics Technology Institute (KETI)	kr
P-079	Reliability of the Flexible Airbag Sensor Module Directly Bonded to Automotive Body with Epoxy Adhesive	Jeong-Cheol Jang, So-Jeong Lee, Jun-Ki Kim	Korea Institute of Industrial Technology (KITECH)	kr
P-080	Microwave Micro-welding of Silver Nanowires Networks for Transparent Flexible Electrode	Jong-Min Jeong, Tae-Ik Lee, Seung-Boo Jung, Min-Su Kim	Korea Institute of Industrial Technology (KITECH), Sungkyunkwan University	kr
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P-082	Development of High-Quality Factor Resonator Using Wafer Level Vacuum Packaging Process	Keunhoi Kim, Yeeun Na, Gapseop Sim, Heeyeoun Kim, Chung Mo Yang	National Nano Fab Center (NNFC)	kr
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P-084	Effects of Annealing Condition on the Interfacial Reaction Characteristics of Cu/Sn-1.8Ag/Au/Ni Microbump by Laser-assisted Bonding Process	Kyeongsoo Kim, Gahui Kim, Chanmi Lee, Jiho Joo, Kwang-Seong Choi, Young-Bae Park	Andong National University, Electronics and Telecommunications Research Institute (ETRI)	kr
P-085	Effect of Underfill Filler Content on Thermal Reliability and Moisture Sorption of Underfill Packaged BGA Components	Jang Baeg Kim, Eun Ha, Kyung-Yeol Kim, Seung-Boo Jung	Sungkyunkwan University	kr
P-086	Effects of Post-annealing Condition on the Bonding Characteristics of Cu/Sn-3.0Ag-0.5Cu/Al Structure for Heat Dissipation Module	Dong Ik Jeong, Doheon Kim, Gahui Kim, Chan Yang Lee, Minchul Oh, Geon-Hong Kim, Young-Bae Park	Andong National University, Institute for Advanced Engineering (IAE)	kr
P-087	Interfacial Bonding Characteristics of Non-cyanide Gold Bump for Display IC Bonding	Hyejin Kim, Gahui Kim, Jahyeon Kim, Yong-Ho Ko, Chul-Min Baek, Joo-hyeon Park, Young-Bae Park	Andong National University, Korea Institute of Industrial Technology (KITECH), LT Metal Co.,Ltd.	kr
P-088	A Study on the Effect of Operating Temperature on the Thermoelectric Modules	Yunho Jung, Kyeong-Ho Shin, Young-Jun Lee, Joo-Hyung Kim	Inha University	kr
P-089	Prediction of Reliability of Lead-Free Solder Joint Interface Using Machine Learning Algorithm in Thermal Shock Reliability Test	Sanggyu Choi, Soongkeun Hyun, Joohyung Kim	Inha University	kr
P-090	Warpage Behavior for Various Copper Clad Laminate in Fan-out Panel Level Package	Taejoon Noh, Sea Hwan Kim, Haksan Jeong, Seung-Boo Jung	Sungkyunkwan University	kr
P-091	The Effect of Underfill Filler Content on the Thermal Reliability of BGA Components Packaged with Underfill	Eun Ha, Jang Baeg Kim, Kyung-Yeol Kim, Seung-boo Jung	Sungkyunkwan University	kr
P-092	Thermal Stress Distribution in Cu Redistribution Lines Measured by X-ray Nanodiffraction	Wei-You Hsu, I-Hsin Tseng, Ching-Yu Chiang, K. N. Tu, Chih Chen	National Yang Ming Chiao Tung University, National Synchrotron Radiation Research Center, City University of Hong Kong	tw
P-093	An Analysis of Factors Affecting on Package of the Structural Robustness Verification Methods Using FEM Simulation	Min Kyu Kang	Seoul National University, SK hynix Inc.	kr
P-094	Investigation on the Thermo-mechanical Behavior of Semiconductor Package Considering Moisture Effect Through Finite Element Analysis	Hui-Jin Um, Dae-Woong Lee, Mi-Jung Lee, Hak-Sung Kim	Hanyang University, SK hynix Inc.	kr
P-095	Fluorine-doped Titania RRAM Fabricated Using Atomic Layer Deposition	Minjae Kim, Dong-eun Kim, Akendra Singh Chabungbam, Atul Thakre, Hyung-Ho Park	Yonsei University	kr
P-096	Passivated Oxygen Vacancy in N/F co-doped ZnO Using H_2O_2 Oxidant and Improved ZnO Homogenous P-n Junction Performance	Hyung-Ho Park, Minjae Kim, Dong-eun Kim, Akendra Singh Chabungbam	Yonsei University	kr
P-097	Detection of Micro-defects Inside Integrated Circuit Packages Training Terahertz Signals Based on Convolutional Neural Network	Heon-Su Kim, Dong-Woon Park, Hak-Sung Kim	Hanyang University	kr
P-098	Elastic Property Estimation of Attenuative Isotropic Material Using V(z) Technique	Young Hun Kim, Hyeong Geun Jo, Ki Chang Kang, Do Yeong Joung, Kwan Kyu Park	Hanyang University	kr
P-099	Analysis of HfO_2 ALD Processes for the Surface Passivation of a CMOS Image Sensor Application	Vijay D. Chavan, Honggyun Kim, Kalyani D. Kadam, Harshada Patil, Jamal Aziz, Tukaram D. Dongale, Muhammad Farooq Khan, Kyeong-Keun Choi, Deok-kee Kim	Sejong University, Shivaji University, Pohang University of Science and Technology	kr
P-100	Measurement of Anisotropic Mechanical Properties with Digital Image Correlation During Spherical Indentation	Soo-Hyun Kim, Hyejin Son, Jong-Hyup Lee, Young-Cheon Kim	Andong National University	kr
P-101	3D Surface Profilometry for Microelectronics by Scanning Repetition Rate of Femtosecond Laser	Jiyong Park	Korea Institute of Industrial Technology (KITECH), University of Science and Technology (UST)	kr
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P-103	Design of a Broadband Coaxial-to-ACP Transition for K-band GSG Probe	Yunsik Park, Deokjin Seo, Jongin Ryu	Korea Electronics Technology Institute (KETI)	kr
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P-105	The Enhancement of Copper to Copper Direct Bonding Process Using Current-induced Bonding Method	Byungkwan Kwak, Jungjun Park, Soojin Kim, Jinmyeong Seo, Haneul Han, Inseong Hwang, Bongyoung Yoo	Hanyang University	kr
P-106	Evaluation of Etching Properties According to the Crystallographic Microstructure of Nickel Thin Film	Yu-Jin Song, Young-Jun Cho, Han-Kyun Shin, Jung Han Kim, Hyo-Jong Lee	Dong-A University	kr
P-107	Analysis of Electrochemical Behavior of Organic Additives during Electroplating of Copper Foil for Secondary Battery	Young-Seo Kim, Han-Kyun Shin, Hyun Park, Hyo-Jong Lee	Dong-A University	kr
P-108	Pulse Plating to Improve Step Coverage of Co Plating in Mm-size Trench Pattern	Ki-Young Lee, Seung-Hyeon Lee, Han-Kyun Shin, Jung-Han Kim, Hyo-Jong Lee	Dong-A University	kr
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P-110	Ammonia Plasma Surface Treatment for Reduction Voids in Cu-Cu Bonding	Ho-Jeong Jeon, Sang Jeen Hong	Myoungji University	kr
P-111	Investigation of Cu-Cu Bonding Interface in Hybrid Bonding	Hyeok-Jin Chu, Injoo Kim, Siye Lee, Woo Kyung Lee, Sungdong Kim	Seoul National University of Science and Technology	kr